**Product End-of-Life Disassembly Instructions**

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

| HP Compaq Elite 8300 MT PC |

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>2</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td></td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td></td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>eg:Acbel EPA PSU,detail information refer to note 1.</td>
<td>3</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing refractory ceramic fibers

Components, parts and materials containing radioactive substances

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver</td>
<td>T-15</td>
</tr>
<tr>
<td>Micro shear</td>
<td>170II</td>
</tr>
<tr>
<td>Screwdriver</td>
<td>PH1</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the access panel.(see Figure 1 below)
2. Disconnect the cables from fan duct and the board. Remove the system fan from chassis.(see Figure 2-6 below)
3. Remove Bezel ,ODD and HDD from chassis.(see Figure 7-11 below)
4. Remove PSU from chassis.(see Figure 12-13 below)
5. Remove rear system fan from chassis.(see Figure 14-15 below)
6. Remove FIO,Power LED and speaker from chassis.(see Figure 16-18 below)
7. Remove the Memory card from the board.(see Figure 19 below)
8. Remove the heatsink and CPU from the board.(see Figure 20-22 below)
9. Remove the battery from the system board.(see Figure 23 below)
10. Remove M/B from chassis.(see Figure 24-25 below)
11. Remove ODD lock and HDD lock from chassis.(see Figure 25-26 below)
12. Remove cable clip from chassis.(see Figure 28 below)
13. Remove fan from fan duct.(from system fan see Figure 29-30 beloe)
14. Remove the fan guard from fan.(see Figure 31 below)
15. Remove the rear fan guard from fan.(the same as front fan see Figure 31 below)
16. Remove PSU cover.(see Figure 32&33 below)
17. Remove PSU PCA.(see Figure 34&35 below)
18. Remove PSU Fan from PSU.(see Figure 36 below)
19. Disconnect all the cables and remove the Electrolytic Capacitors.(see Figure 37-39 below)

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Figure 1 Remove the access panel:

Figure 2 Disconnect the cables from fan duct

Figure 3 Disconnect the cables from the MB

Figure 4 Remove front system fan from the chassis

Figure 5 Disconnect CPU Power cable from the MB

Figure 6 Disconnect other PSU cables from the MB

PSG instructions for this template are available at EL-MF877-01
Figure 7 Disconnect SATA cable from ODD

Figure 8 Disconnect SATA cable from HDD

Figure 9 Remove front panel

Figure 10 Remove the ODD from cage

Figure 11 Loose the PSU’s screw from chassis

Figure 12 Remove the PSU from Cage

PSG instructions for this template are available at EL-MF877-01
Figure 13 Loose the Rear fan's screw from chassis

Figure 14 Remove Rear system fan

Figure 15 Loose the screws of FIO and remove it

Figure 16 Remove the Power LED cable

Figure 17 Loose the screws of speaker and remove it

Figure 18 Remove the Memory card from the board
Figure 19: Loosen the screws and remove heat sink

Figure 20: Rotate the handle and open it up

Figure 21: Remove the CPU from the board

Figure 22: Remove the battery from the system board

Figure 23: Remove the battery from the system board

Figure 24: Loosen the screws of MB from chassis

PSG instructions for this template are available at EL-MF877-01
<table>
<thead>
<tr>
<th>Figure 25</th>
<th>Remove M/B from chassis</th>
</tr>
</thead>
<tbody>
<tr>
<td>Figure 26</td>
<td>Remove the ODD lock from chassis</td>
</tr>
<tr>
<td>Figure 27</td>
<td>Remove the HDD lock from chassis</td>
</tr>
<tr>
<td>Figure 28</td>
<td>Remove cable clip from chassis</td>
</tr>
<tr>
<td>Figure 29</td>
<td>Loose the screws of fan from the fan duct</td>
</tr>
<tr>
<td>Figure 30</td>
<td>Remove the system fan from fan duct</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Figure 31 Remove the fan guard from fan

Figure 32 Remove the screws on the PSU chassis

Figure 33 Lift the cover off the power supply

Figure 34 Remove the four screws on the board

Figure 35 Remove the power supply PCA from the power supply chassis

Figure 36 Remove the Electrolytic Capacitors(For Liteon 320W EPA PSU)
Figure 37 Remove the Electrolytic Capacitors (For Acbel 320W EPA)

Figure 38 Remove the Electrolytic Capacitors (For Chicony 320W STD)

Figure 39 Remove the Electrolytic Capacitors (For Delta 320W EPA)

Figure 40 Remove the Electrolytic Capacitors (For Delta 320W STD)

Figure 41 Remove the Electrolytic Capacitors (For Bestec 320W STD)

Figure 42 Remove the Electrolytic Capacitors (For Bestec 320W EPA)

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